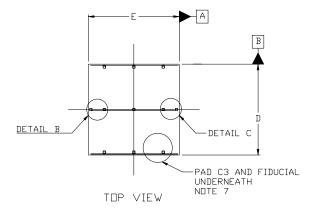


## ODCSP8 3.16x3.16x0.64

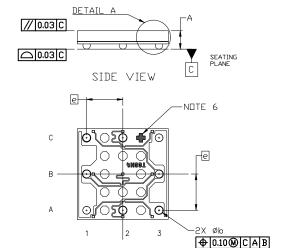
CASE 570CS ISSUE A

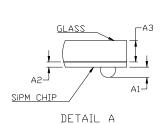
**DATE 07 MAY 2019** 



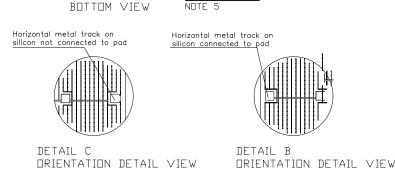
## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
- 6. DRIENTATION FIDUCIAL LOCATION. LOCATED BETWEEN PADS C2 AND C3.
- REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.





•	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.59	0.64	0.69	
A1	0.15	0.18	0.20	
A2	0.075	0.090	0.105	
A3	0.355	0.370	0.385	
b	0.23	0.26	0.29	
D	3.11	3.16	3.21	
Ε	3.11	3.16	3.21	
e	1.26 BSC			



1.26
PITCH

SOLDER MASK APERTURE

1.26
PITCH

SUBJECT MASK APERTURE

8X Ø0.47

SUBJECT MASK APERTURE

8X Ø0.27

CUPPER PAD

RECOMMENDED

MOUNTING FOOTPRINT\*
NSMD TYPE

For additional information on our Pb-Free strategy and soldering details, please download the DN Seniconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	ODCSP8 3.16x3.16x0.64		PAGE 1 OF 1	

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